

SPARC64TM +:

HAL's Second Generation 64-bit SPARC Processor

HAL Computer Systems

Fujitsu Limited



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OUTLINE

- . SPARC64+ Project Goals**
- . SPARC64 Overview**
- . Improvements over SPARC64**
- . SPARC64+ Performance Data**
- . Summary**



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SPARC64+ Project Goals

- Improvements over HAL's first generation SPARC64 Processor
 - ♦ Improved Performance.
 - ♦ Performance Monitor Support.
 - ♦ Size Reduction.
 - ♦ Increased Debug Visibility.
 - ♦ Complete software compatibility with SPARC64.

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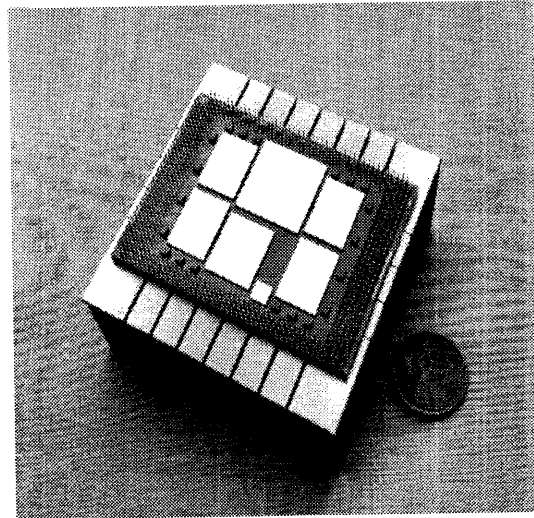
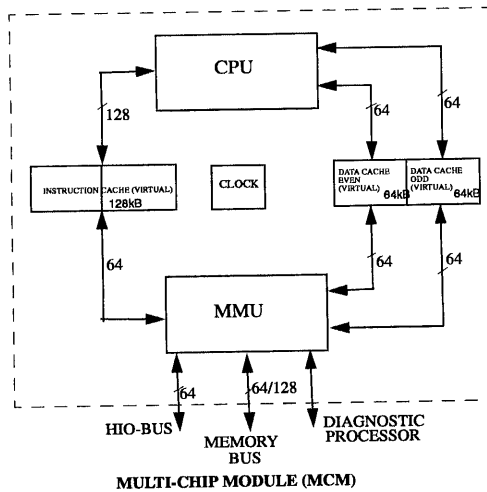
SPARC64 Overview (First Generation)

- SPARC64 Processor Module is a ceramic MCM with
 - ♦ One CPU
 - ♦ Four CACHE Chips
 - ♦ One MMU and
 - ♦ One CLOCK chip

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SPARC64 Overview (First Generation)....



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SPARC64 Overview (First Generation)....

. CPU

- ◆ Superscalar, 4 issue, true 64 bit, V9-SPARC Implementation.
- ◆ Four stage Fixed-Point Instruction Pipeline .
- ◆ Six stage Load Instruction Pipeline.

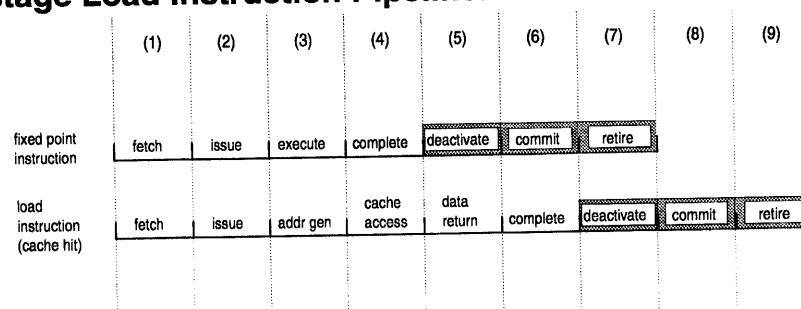


Figure 1: Pipeline Stages in SPARC64 CPU

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SPARC64 Overview (First Generation)....

- ♦ Up to 64 Active instructions tracked through Dataflow execution.
- ♦ Employs Register Renaming, Dynamic Branch Prediction.
- ♦ ISSUE *in-order*, EXECUTE/COMPLETE *Out-of-order* and COMMIT *in-order*.
- ♦ Contains 2 Load/Store Units, 2 Fixed Point Units, 2 Address Generation units, 1 Floating Point Multiply Add unit and a Self timed Floating Point Divide Unit.

• CACHE

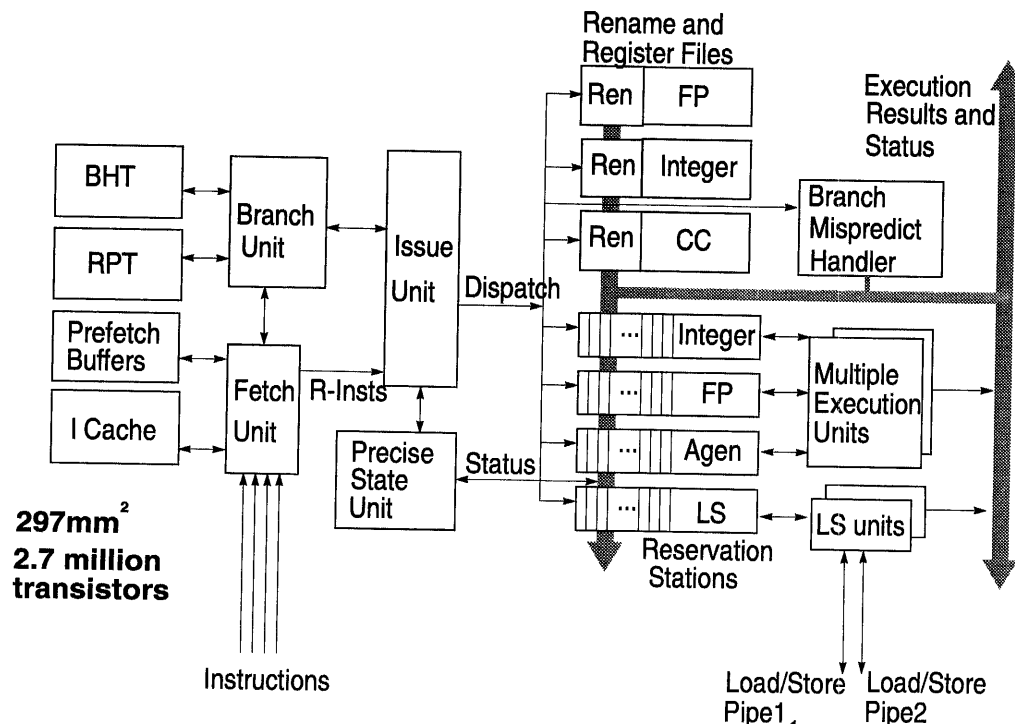
- ♦ Non-Blocking, with virtual index and virtual tag.
- ♦ Each chip is 64kB, can service 2 independent requests from CPU .
- ♦ 4 way set associative.
- ♦ Services Speculative/out-of-order CPU requests .
- ♦ 2 Instruction Cache chips, 2 Data Cache Chips.

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SPARC64 CPU Block Diagram



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SPARC64 Overview (First Generation)....

. MMU

- ♦ Interfaces with Virtual Caches, Memory system, I/O, and Diagnostic Processor..
- ♦ A Linear 64-Bit Address Space supported through 2 level translations and 3 level memory hierarchy (Virtual, Logical and Physical Addresses).

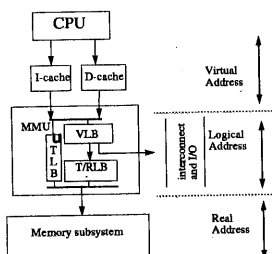
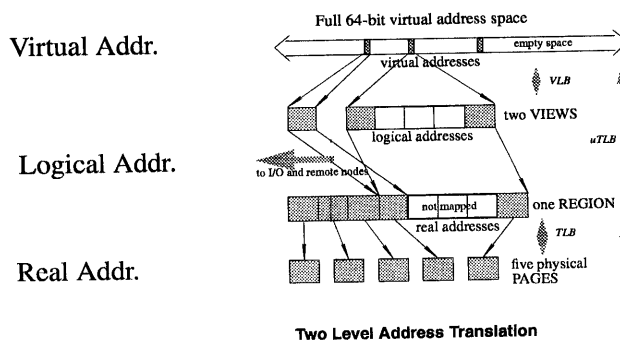


FIGURE 2. Address translation flow



- ♦ 3 “lookaside buffers” reduce time for translation
 - 128-entry, fully associative VLB (VA -->LA)
 - 1024 entry, 4 way associative TLB (LA -->PA) and
 - 8 entry, 3 port, fully associative microTLB(VA-->PA).
- ♦ Contains a 1024 entry Data Cache Real Address Table.
 - Stores Real Address Tags of all Data Cache lines.
 - An entry match => real hit but virtual cache miss => no memory access required and cache line is re-tagged..



SPARC64 Overview (First Generation)....

. CLOCK

- ♦ Under Diagnostic Processor Control, provides SYS-CLK/ SCAN-CLK for all other MCM chips and Memory Subsystem.
- ♦ Freq : 15~280MHz, Jitter 80~160ps, Programmable Delay Lines to control skews.

. PROCESS

- ♦ Fujitsu's twin-well 0.4 μ , 4 layer-metal , CS55 CMOS process.
- ♦ 3 Metal layers for Signal routing.
- ♦ 4th Metal layer for Bonding Pads, Global Power, Clock Routing .
- ♦ Solder Bump Bonding for MCM-chip interconnection.

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SPARC64+ Improvements (Performance)

- Cycle Time speedup ~20% in CPU
 - ♦ Fujitsu's faster CS60-process , smaller die size .
 - ♦ Removed 2 levels of logic from SPARC64 CPU long paths.
 - ♦ Improved/Fine-tuned Critical Timing Paths using
 - Faster Fixed/Floating Point - Register Files (Aggressive Circuits).
 - Faster Caches, Macros(Circuits).
 - Wider Instruction recoding (changed from 38 to 44 bits - requires less decoding in the fetch cycle).
 - More aggressive Execution Selection Algorithm.
 - Modified "Queue-slot-Available--> Instruction Issue Valid" Protocol.

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SPARC64+ Improvements (Performance)..

• Micro Architectural Changes to improve IPC*

- ♦ Fixed Point register file modifications : +2.9%
 - Physical register size increased from 116 to 128.
 - Number of Register Windows increased from 4 to 5.
- ♦ CPU on-chip Instruction Cache Size increased from 1k to 2k instructions : +3.0%.
- ♦ Branch History Table Size Increase, Improved Memory Instruction scheduling: +2.0%.

* measured by SPECINT92 , All improvement predictions based on "Timer" - HAL developed Performance Evaluation Tool.



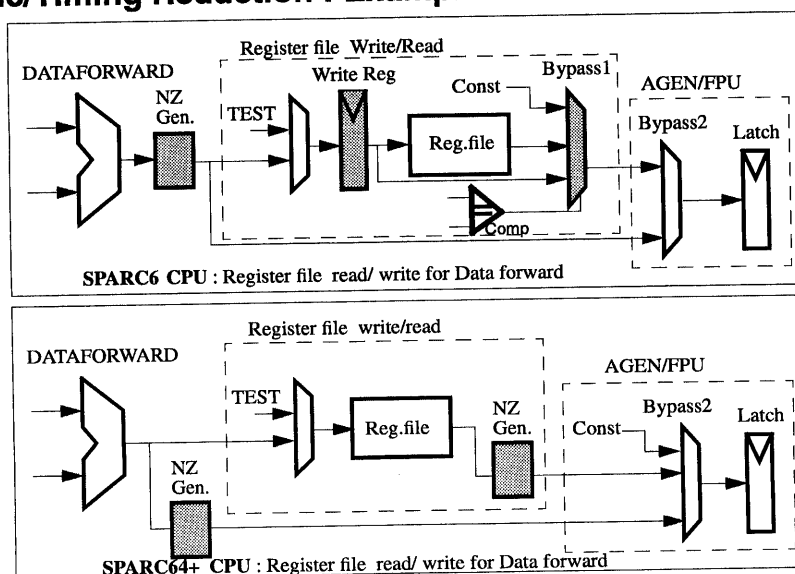
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SPARC64+ Improvements (Performance)..

♦ Logic/Timing Reduction : Example



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SPARC64+ Improvements (Performance)..

- N(egative), Z(ero) bits not stored in Register File.
- Dataforward results written into Reg.file one cycle earlier.
- Enables removal of bypass muxes/comparators in Reg.file read path and hence in timing. (10 read ports).

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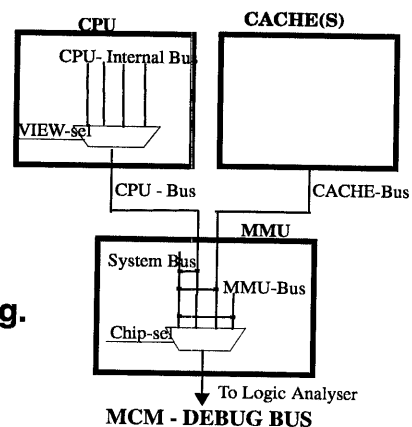
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SPARC64+ Improvements(Debug)

• Chips on MCM are flip mounted.

- ♦ MCM chips can't be probed for tests.
- ♦ SPARC64 Processor chips provide dedicated MCM visible signals for Logic Analyser hookup during Debug.
- ♦ Added more signals for tracking internal chip states.



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SPARC64+ Improvements ..(Debug)

- CPU related Debug Bus (89 bits) has 4 views.
 - ♦ 1. Instruction Tracking Bus View.
 - ♦ 2. Instruction Fetch Bus View.
 - ♦ 3. Load Store Bus View.
 - ♦ 4. CPU- Internal State View

SPARC64+ Improvements (Perf.Monitoring)

- ♦ SPARC64 MMU incorporates Performance counters for
 - observing Lookaside Buffer(s) performance.
 - Cache hit/miss rates, Data cache replacement rates.
- ♦ In SPARC64+, CPU Performance Monitoring features added.
 - HAL implementation specific architecture feature.
 - Software visible and privileged.
 - Kept it simple though the system supports Speculative/ out-of-order executions, Retry/Block condition and Instruction/Data Pre-fetches.

SPARC64+ Improvements **(Perf.Monitoring)..**

- Performance Monitors/Counters in CPU provided to
 - Count Instruction Issue stalls due to Fetch,Resources (Execution units, Reservation Stations, Free Registers) and Precise State Exceptions.
 - Measure Instruction Issue/Commit rates.
 - Measure Total Latency of Memory accesses.
 - Measure Data Cache Hit Rates.
 - Measure Memory Access rates.
- Count Accumulation/Monitor interval period:100msec.

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SPARC64+ Improvements (Size **Reduction)**

- ♦ SPARC64+, CPU die size: $\sim 200\text{mm}^2$
- ♦ 33% reduction over SPARC64 CPU due to
 - reduction in metal pitch.
 - reduced transistor feature size.
 - addition of 5th metal layer for routing.

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SPARC64+ Performance Data

- **Performance Improvement over SPARC64 (due to hardware only)**

Estimated Performance change for SPARC64+

Description	Improvement
Cycle Time improvement	20%
IPC improvements ¹	8%
Total (1.08X1.20) -1	~30%

1. refer to Functional Changes section.

SUMMARY

- ♦ **30% performance improvement over SPARC64 is achieved in hardware through *Cycle Time Reduction* , *Addition of on-chip resources* and *Micro-architectural changes*.**
- ♦ **Performance monitoring counters added in CPU to**
 - **observe/analyse the system behavior.**
 - **fine-tune/optimize Compilers.**
- ♦ **Chip Size reduced by 33% .**
- ♦ **Wider Debug Bus increased the observability of the system during Hardware Debug.**
- ♦ **Existing System Software/Binaries for SPARC64 will run efficiently on SPARC64+, without any changes.**
- ♦ **Restricted the micro-architectural changes to meet short development schedule requirements.**
- ♦ **Design Tool Flow changes, Verification Efforts due to the changes were kept minimal.**

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